

Name	Type	Description	Curing	Curing condit.	Viscosity	C.T.E	Feature
DA90	Conductive Adhesive	DA... is a silver filled, highly electrically conductive, solvent-free and fast cure thermosetting die attach adhesives	Temp. Cure	30-50min cure @ 90°C	10-50k cp	35	Thermal Conductivity 2-5W/mK
DA150				6-10min cure @ 150°C	10-50k cp	35	Volume resistivity 0.00003-0.00008Ω.cm
DA150L				6-10min cure @ 150°C	2-5k cp	32	Thermal Conductivity > 2.8W/mK
DA150LE	Insulating Die Attach Adhesive	DA150LE/LW is one-component, thermosetting insulating transparent die attach adhesives which has been designed for LED chip (GaN) bonding	Temp. Cure	60min cure @ 150°C	5-10k cp	65	Thermal Conductivity > 0.4W/mK
DA150LW				5-10min @ 150°C	5-10k cp	25 - 30	Thermal Conductivity > 0.9W/mK
TM150	Solderable Conductive Adhesive	TM... solderable conductive adhesives is rapid cure, self-filling, self-leveling and self-soldering adhesives	Temp. Cure	5min cure @ 150°C	500k cp	23.5	Thermal Conductivity 60W/mK
TM230				60sec cure @ 230°C	30-45k cp	21.7	Thermal Conductivity 58W/mK
WL66O	Die Attach Adhesive	Dual cure UV bonding adhesives	UV Cure	3-5sec	3-6k cp	α1 = 65	Tg @ 120°C
WL66H		Low temperature thermal cure die attach adhesives	Temp. Cure	1,5-2hrs @ 100°C	2-5k cp		Transparent colorless liquid
NCA88	Non Conductive Adhesive	NCA88 is a non-conductive adhesive which is designed to bond rigid substrates to glass or metal.	Temp. Cure	In-line curing or 10-15min @ 80-90°C	15-50k cp	α1 = 75 α2 = 182	Lap Shear Strength 2000psi (FR4/FR4)
NCA180		NCA180 non-conductive adhesive is designed for thermal compression bonding application		10-30sec @ 180°C	3-8k cp	α1 = 21 α2 = 131	Lap Shear Strength 4500psi (FR4/FR4)
SMT256	Dip Adhesive	SMT2.. series adhesives have been designed to enhance solder joint reliability and eliminate solder joint cracking for CSP, BGA, Flip-Chip and PoP	Temp. Cure	4-5min @ 230°C	10-50k cp		First solder joint encapsulating adhesive
SMT266	Spray Adhesive				6-10 cp		
SMT158	Underfill	SMT158/160 capillary underfill is a combination of capillary flow and no-flow underfill	Temp. Cure	In-line curing or 15min @ 150°C	3.5-8.0k cp	α1 = 35 α2 = 142	Lap Shear Strength 2600psi (FR4/FR4)
SMT160					1.5-2.5k cp	α1 = 70 α2 = 272	Lap Shear Strength 2480psi (FR4/FR4)
SMT156	Solderable Adhesive	SMT156 is rapid cure, self-leveling and self-soldering adhesive	Temp. Cure	5min cure @ 150°C	700-900k cp	23.5	Electrical conductivity >10 ⁸ S/m

Note: All specifications are subject to change without notice



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